AMD Xilinx - XC3S200-4FT256I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	480
Number of Logic Elements/Cells	4320
Total RAM Bits	221184
Number of I/O	173
Number of Gates	200000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s200-4ft256i

Table 3 shows the number of user I/Os as well as the number of differential I/O pairs available for each device/package combination.

Table 3: **Spartan-3 Device I/O Chart**

Available User I/Os and Differential (Diff) I/O Pairs by Package Type																				
Package	**VQ100 VQG100**		**CP132(1) CPG132**		**TQ144 TQG144**		**PQ208 PQG208**		**FT256 FTG256**		**FG320 FGG320**		**FG456 FGG456**		**FG676 FGG676**		**FG900 FGG900**		**FG1156(1) FGG1156**	
Footprint (mm)	**16 x 16**		**8 x 8**		**22 x 22**		**30.6 x 30.6**		**17 x 17**		**19 x 19**		**23 x 23**		**27 x 27**		**31 x 31**		**35 x 35**	
Device	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**
XC3S50	63	29	89(1)	44(1)	97	46	124	56	–	–	–	–	–	–	–	–	–	–	–	–
XC3S200	63	29	–	–	97	46	141	62	173	76	–	–	–	–	–	–	–	–	–	–
XC3S400	–	–	–	–	97	46	141	62	173	76	221	100	264	116	–	–	–	–	–	–
XC3S1000	–	–	–	–	–	–	–	–	173	76	221	100	333	149	391	175	–	–	–	–
XC3S1500	–	–	–	–	–	–	–	–	–	–	221	100	333	149	487	221	–	–	–	–
XC3S2000	–	–	–	–	–	–	–	–	–	–	–	–	333	149	489	221	565	270	–	–
XC3S4000	–	–	–	–	–	–	–	–	–	–	–	–	–	–	489	221	633	300	712(1)	312(1)
XC3S5000	–	–	–	–	–	–	–	–	–	–	–	–	–	–	489	221	633	300	784(1)	344(1)

Notes:

1. The CP132, CPG132, FG1156, and FGG1156 packages are discontinued. See http://www.xilinx.com/support/documentation/spartan-3_customer_notices.htm.
2. All device options listed in a given package column are pin-compatible.
3. User = Single-ended user I/O pins. Diff = Differential I/O pairs.

Package Marking

Figure 2 shows the top marking for Spartan-3 FPGAs in the quad-flat packages. Figure 3 shows the top marking for Spartan-3 FPGAs in BGA packages except the 132-ball chip-scale package (CP132 and CPG132). The markings for the BGA packages are nearly identical to those for the quad-flat packages, except that the marking is rotated with respect to the ball A1 indicator. Figure 4 shows the top marking for Spartan-3 FPGAs in the CP132 and CPG132 packages.

The "5C" and "4I" part combinations may be dual marked as "5C/4I". Devices with the dual mark can be used as either -5C or -4I devices. Devices with a single mark are only guaranteed for the marked speed grade and temperature range. Some specifications vary according to mask revision. Mask revision E devices are errata-free. All shipments since 2006 have been mask revision E.

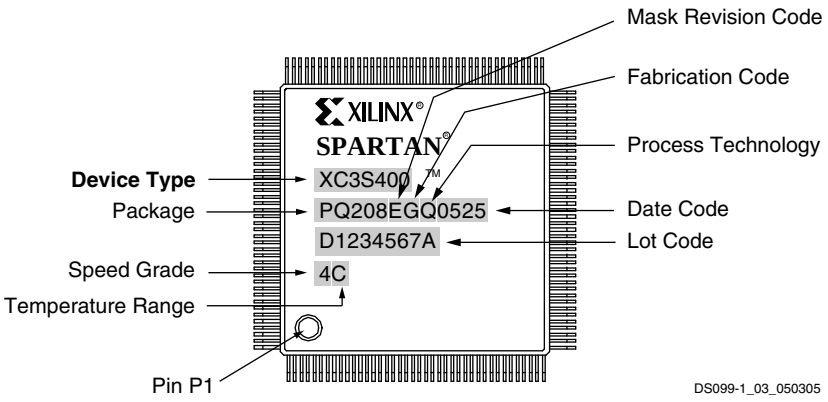


Figure 2: **Spartan-3 FPGA QFP Package Marking Example for Part Number XC3S400-4PQ208C**

Supply Voltages for the IOBs

Three different supplies power the IOBs:

- The V_{CCO} supplies, one for each of the FPGA's I/O banks, power the output drivers, except when using the GTL and GTLP signal standards. The voltage on the V_{CCO} pins determines the voltage swing of the output signal.
- V_{CCINT} is the main power supply for the FPGA's internal logic.
- The V_{CCAUX} is an auxiliary source of power, primarily to optimize the performance of various FPGA functions such as I/O switching.

The I/Os During Power-On, Configuration, and User Mode

With no power applied to the FPGA, all I/Os are in a high-impedance state. The V_{CCINT} (1.2V), V_{CCAUX} (2.5V), and V_{CCO} supplies may be applied in any order. Before power-on can finish, V_{CCINT}, V_{CCO} Bank 4, and V_{CCAUX} must have reached their respective minimum recommended operating levels (see Table 29, page 59). At this time, all I/O drivers also will be in a high-impedance state. V_{CCO} Bank 4, V_{CCINT}, and V_{CCAUX} serve as inputs to the internal Power-On Reset circuit (POR).

A Low level applied to the HSWAP_EN input enables pull-up resistors on User I/Os from power-on throughout configuration. A High level on HSWAP_EN disables the pull-up resistors, allowing the I/Os to float. If the HSWAP_EN pin is floating, then an internal pull-up resistor pulls HSWAP_EN High. As soon as power is applied, the FPGA begins initializing its configuration memory. At the same time, the FPGA internally asserts the Global Set-Reset (GSR), which asynchronously resets all IOB storage elements to a Low state.

Upon the completion of initialization, INIT_B goes High, sampling the M0, M1, and M2 inputs to determine the configuration mode. At this point, the configuration data is loaded into the FPGA. The I/O drivers remain in a high-impedance state (with or without pull-up resistors, as determined by the HSWAP_EN input) throughout configuration.

The Global Three State (GTS) net is released during Start-Up, marking the end of configuration and the beginning of design operation in the User mode. At this point, those I/Os to which signals have been assigned go active while all unused I/Os remain in a high-impedance state. The release of the GSR net, also part of Start-up, leaves the IOB registers in a Low state by default, unless the loaded design reverses the polarity of their respective RS inputs.

In User mode, all internal pull-up resistors on the I/Os are disabled and HSWAP_EN becomes a "don't care" input. If it is desirable to have pull-up or pull-down resistors on I/Os carrying signals, the appropriate symbol—e.g., PULLUP, PULLDOWN—must be placed at the appropriate pads in the design. The Bitstream Generator (Bitgen) option UnusedPin available in the Xilinx development software determines whether unused I/Os collectively have pull-up resistors, pull-down resistors, or no resistors in User mode.

CLB Overview

For more details on the CLBs, refer to the chapter entitled "Using Configurable Logic Blocks" in UG331.

The Configurable Logic Blocks (CLBs) constitute the main logic resource for implementing synchronous as well as combinatorial circuits. Each CLB comprises four interconnected slices, as shown in Figure 11. These slices are grouped in pairs. Each pair is organized as a column with an independent carry chain.

The nomenclature that the FPGA Editor—part of the Xilinx development software—uses to designate slices is as follows: The letter 'X' followed by a number identifies columns of slices. The 'X' number counts up in sequence from the left side of the die to the right. The letter 'Y' followed by a number identifies the position of each slice in a pair as well as indicating the CLB row. The 'Y' number counts slices starting from the bottom of the die according to the sequence: 0, 1, 0, 1 (the first CLB row); 2, 3, 2, 3 (the second CLB row); etc. Figure 11 shows the CLB located in the lower left-hand corner of the die. Slices X0Y0 and X0Y1 make up the column-pair on the left where as slices X1Y0 and X1Y1 make up the column-pair on the right. For each CLB, the term "left-hand" (or SLICEM) indicates the pair of slices labeled with an even 'X' number, such as X0, and the term "right-hand" (or SLICEL) designates the pair of slices with an odd 'X' number, e.g., X1.

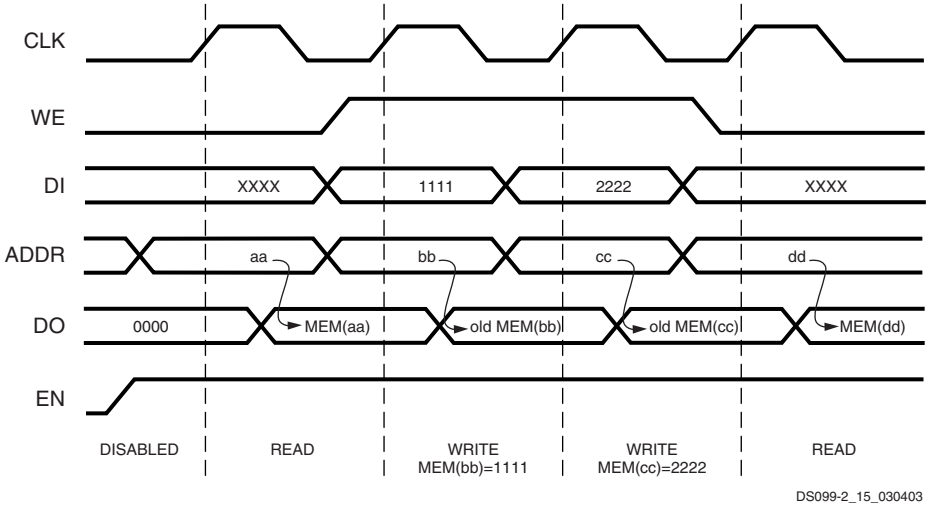


Figure 16: **Waveforms of Block RAM Data Operations with READ_FIRST Selected**

Choosing a third attribute called NO_CHANGE puts the DO outputs in a latched state when asserting WE. Under this condition, the DO outputs will retain the data driven just before WE was asserted. NO_CHANGE timing is shown in the portion of Figure 17 during which WE is High.

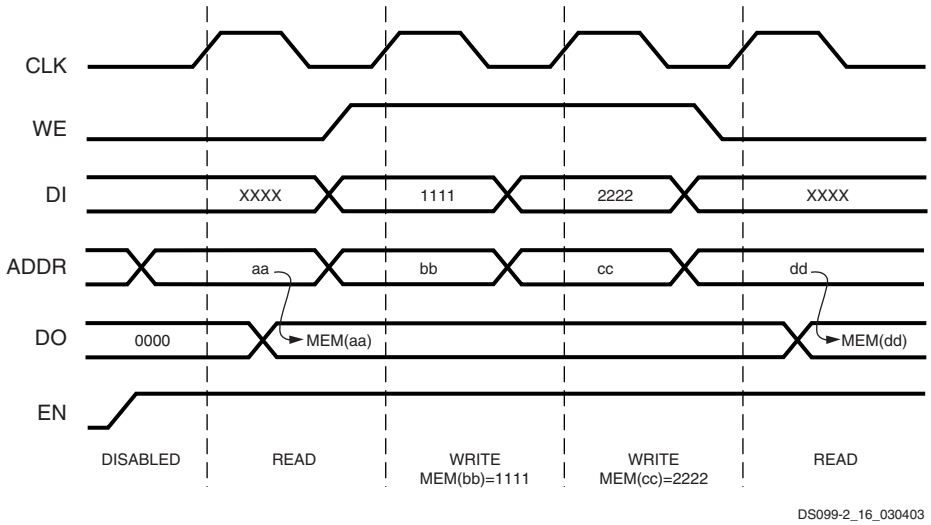


Figure 17: **Waveforms of Block RAM Data Operations with NO_CHANGE Selected**

Dedicated Multipliers

All Spartan-3 devices provide embedded multipliers that accept two 18-bit words as inputs to produce a 36-bit product. This section provides an introduction to multipliers. For further details, refer to the chapter entitled “Using Embedded Multipliers” in UG331.

The input buses to the multiplier accept data in two’s-complement form (either 18-bit signed or 17-bit unsigned). One such multiplier is matched to each block RAM on the die. The close physical proximity of the two ensures efficient data handling. Cascading multipliers permits multiplicands more than three in number as well as wider than 18-bits. The multiplier is placed in a design using one of two primitives: an asynchronous version called MULT18X18 and a version with a register called MULT18X18S, as shown in Figure 18. The signals for these primitives are defined in Table 15.

The CORE Generator system produces multipliers based on these primitives that can be configured to suit a wide range of requirements.

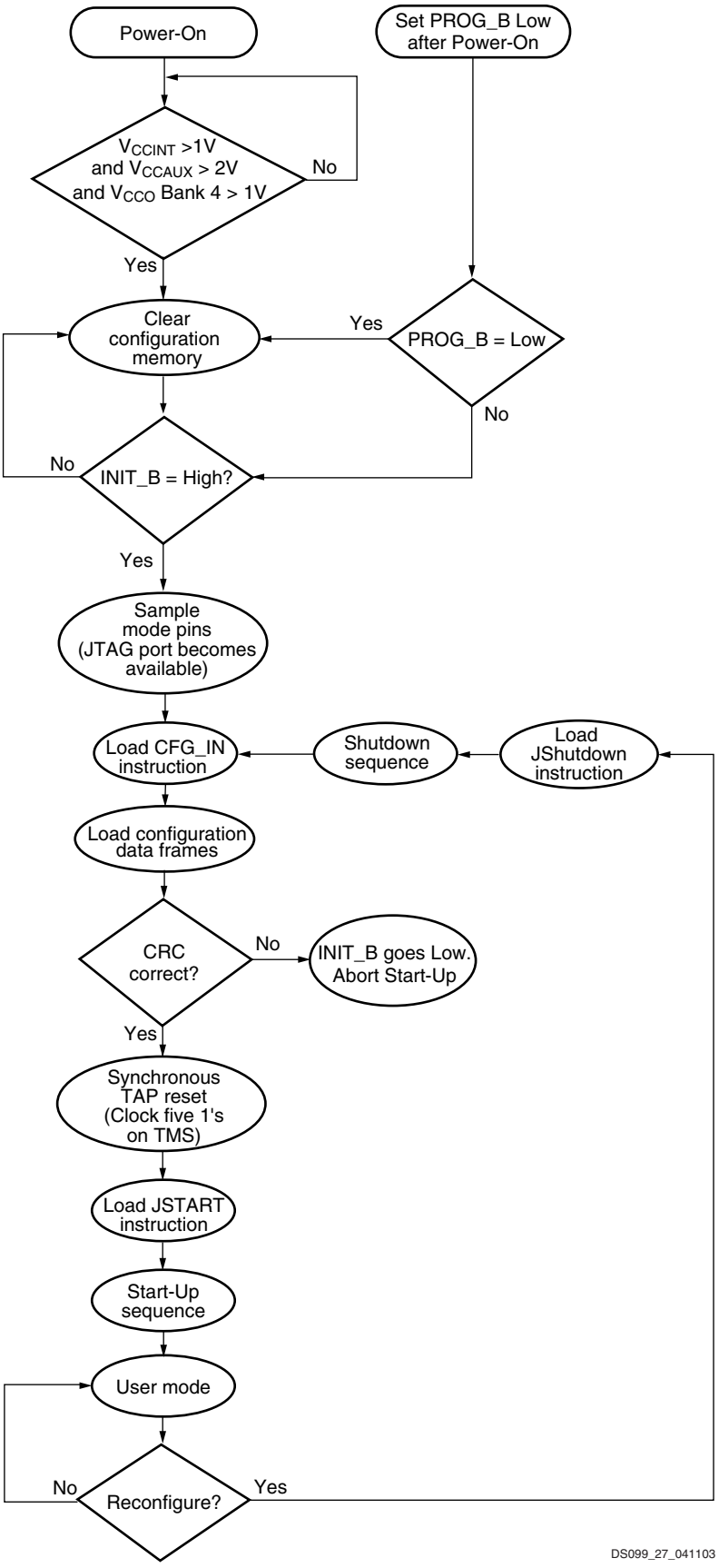


Figure 30: **Boundary-Scan Configuration Flow Diagram**

Additional Configuration Details

Additional details about the Spartan-3 FPGA configuration architecture and command set are available in UG332: *Spartan-3 Generation Configuration User Guide* and in application note XAPP452: *Spartan-3 Advanced Configuration Architecture*.

Powering Spartan-3 FPGAs

Voltage Regulators

Various power supply manufacturers offer complete power solutions for Xilinx FPGAs, including some with integrated multi-rail regulators specifically designed for Spartan-3 FPGAs. The Xilinx Power Corner web page provides links to vendor solution guides as well as Xilinx power estimation and analysis tools.

Power Distribution System (PDS) Design and Bypass/Decoupling Capacitors

Good power distribution system (PDS) design is important for all FPGA designs, especially for high-performance applications. Proper design results in better overall performance, lower clock and DCM jitter, and a generally more robust system. Before designing the printed circuit board (PCB) for the FPGA design, review application note XAPP623: *Power Distribution System (PDS) Design: Using Bypass/Decoupling Capacitors*.

Power-On Behavior

Spartan-3 FPGAs have a built-in Power-On Reset (POR) circuit that monitors the three power rails required to successfully configure the FPGA. At power-up, the POR circuit holds the FPGA in a reset state until the V_{CCINT}, V_{CCAUX}, and V_{CCO} Bank 4 supplies reach their respective input threshold levels (see Table 29, page 59). After all three supplies reach their respective threshold, the POR reset is released and the FPGA begins its configuration process.

Because the three supply inputs must be valid to release the POR reset and can be supplied in any order, there are no specific voltage sequencing requirements. However, applying the FPGA's V_{CCAUX} supply before the V_{CCINT} supply uses the least I_{CCINT} current.

Once all three supplies are valid, the minimum current required to power-on the FPGA is equal to the worst-case quiescent current, as specified in Table 34, page 62. Spartan-3 FPGAs do not require Power-On Surge (POS) current to successfully configure.

Surplus I_{CCINT} if V_{CCINT} Applied before V_{CCAUX}

If the V_{CCINT} supply is applied before the V_{CCAUX} supply, the FPGA may draw a surplus I_{CCINT} current in addition to the I_{CCINT} quiescent current levels specified in Table 34. The momentary additional I_{CCINT} surplus current might be a few hundred milliamperes under nominal conditions, significantly less than the instantaneous current consumed by the bypass capacitors at power-on. However, the surplus current immediately disappears when the V_{CCAUX} supply is applied, and, in response, the FPGA's I_{CCINT} quiescent current demand drops to the levels specified in Table 34. The FPGA does not use nor does it require the surplus current to successfully power-on and configure. If applying V_{CCINT} before V_{CCAUX}, ensure that the regulator does not have a foldback feature that could inadvertently shut down in the presence of the surplus current.

Maximum Allowed V_{CCINT} Ramp Rate on Early Devices, if V_{VCCINT}Supply is Last in Sequence

All devices with a mask revision code 'E' or later do not have a V_{CCINT} ramp rate requirement. See Mask and Fab Revisions, page 58.

Early Spartan-3 FPGAs were produced at a 200 mm wafer production facility and are identified by a fabrication/process code of "FQ" on the device top marking, as shown in Package Marking, page 5. These "FQ" devices have a maximum V_{CCINT} ramp rate requirement if and only if V_{CCINT} is the last supply to ramp, after the V_{CCAUX} and V_{CCO} Bank 4 supplies. This maximum ramp rate appears as T_{CCINT} in Table 30, page 60.

Minimum Allowed V_{CCO} Ramp Rate on Early Devices

Devices shipped since 2006 essentially have no V_{CCO} ramp rate limits, shown in Table 30, page 60. Similarly, all devices with a mask revision code 'E' or later do not have a V_{CCO} ramp rate limit. See Mask and Fab Revisions, page 58.

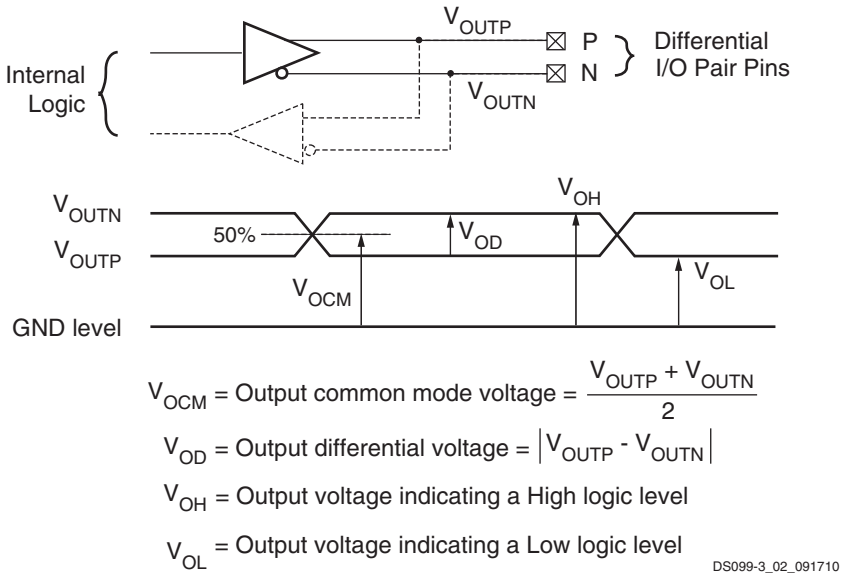


Figure 33: **Differential Output Voltages**

Table 38: **DC Characteristics of User I/Os Using Differential Signal Standards**

Signal Standard	Mask[3] Revision	V_{OD}			V_{OCM}			V_{OH}	V_{OL}
		Min (mV)	Typ (mV)	Max (mV)	Min (V)	Typ (V)	Max (V)	Min (V)	Max (V)
LDT_25 (ULVDS_25)	All	430[4]	600	670	0.495	0.600	0.715	0.71	0.50
LVDS_25	All	100	–	600	0.80	–	1.6	0.85	1.55
	'E'	200	–	500	1.0	–	1.5	1.10	1.40
BLVDS_25[5]	All	250	350	450	–	1.20	–	–	–
LVDSEXT_25	All	100	–	600	0.80	–	1.6	0.85	1.55
	'E'	300	–	700	1.0	–	1.5	1.15	1.35
LVPECL_25[5]	All	–	–	-	–	–	-	1.35	1.005
RSDS_25[6]	All	100	–	600	0.80	–	1.6	0.85	1.55
	'E'	200	–	500	1.0	–	1.5	1.10	1.40
DIFF_HSTL_II_18	All	–	–	–	–	–	–	V_{CCO} – 0.40	0.40
DIFF_SSTL2_II	All	–	–	–	–	–	–	V_{TT} + 0.80	V_{TT} – 0.80

Notes:

1. The numbers in this table are based on the conditions set forth in Table 32 and Table 37.
2. Output voltage measurements for all differential standards are made with a termination resistor (R_T) of 100Ω across the N and P pins of the differential signal pair.
3. Mask revision E devices have tighter output ranges but can be used in any design that was in a previous revision. See Mask and Fab Revisions, page 58.
4. This value must be compatible with the receiver to which the FPGA's output pair is connected.
5. Each LVPECL_25 or BLVDS_25 output-pair requires three external resistors for proper output operation as shown in Figure 34. Each LVPECL_25 or BLVDS_25 input-pair uses a 100W termination resistor at the receiver.
6. Only one of the differential standards RSDS_25, LDT_25, LVDS_25, and LVDSEXT_25 may be used for outputs within a bank. Each differential standard input-pair requires an external 100Ω termination resistor.

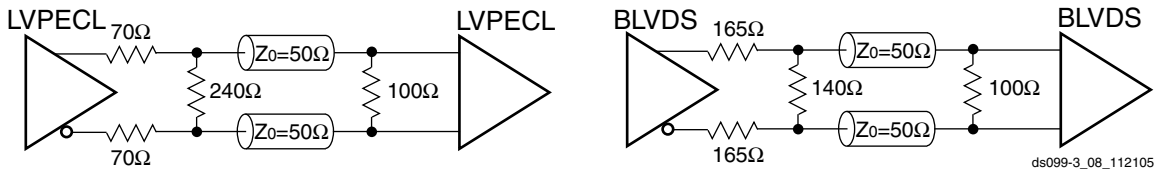


Figure 34: **External Termination Required for LVPECL and BLVDS Output and Input**

I/O Timing

Table 40: **Pin-to-Pin Clock-to-Output Times for the IOB Output Path**

Symbol	Description	Conditions	Device	Speed Grade		Units
				-5	-4	
				Max(2)	Max(2)	
Clock-to-Output Times						
$T_{ICKOFDCM}$	When reading from the Output Flip-Flop (OFF), the time from the active transition on the Global Clock pin to data appearing at the Output pin. The DCM is in use.	LVCMOS25(3), 12 mA output drive, Fast slew rate, with DCM(4)	XC3S50	2.04	2.35	ns
			XC3S200	1.45	1.75	ns
			XC3S400	1.45	1.75	ns
			XC3S1000	2.07	2.39	ns
			XC3S1500	2.05	2.36	ns
			XC3S2000	2.03	2.34	ns
			XC3S4000	1.94	2.24	ns
			XC3S5000	2.00	2.30	ns
T_{ICKOF}	When reading from OFF, the time from the active transition on the Global Clock pin to data appearing at the Output pin. The DCM is not in use.	LVCMOS25(3), 12 mA output drive, Fast slew rate, without DCM	XC3S50	3.70	4.24	ns
			XC3S200	3.89	4.46	ns
			XC3S400	3.91	4.48	ns
			XC3S1000	4.00	4.59	ns
			XC3S1500	4.07	4.66	ns
			XC3S2000	4.19	4.80	ns
			XC3S4000	4.44	5.09	ns
			XC3S5000	4.38	5.02	ns

Notes:

1. The numbers in this table are tested using the methodology presented in Table 48 and are based on the operating conditions set forth in Table 32 and Table 35.
2. For minimums, use the values reported by the Xilinx timing analyzer.
3. This clock-to-output time requires adjustment whenever a signal standard other than LVCMOS25 is assigned to the Global Clock Input or a standard other than LVCMOS25 with 12 mA drive and Fast slew rate is assigned to the data Output. If the former is true, *add* the appropriate Input adjustment from Table 44. If the latter is true, *add* the appropriate Output adjustment from Table 47.
4. DCM output jitter is included in all measurements.

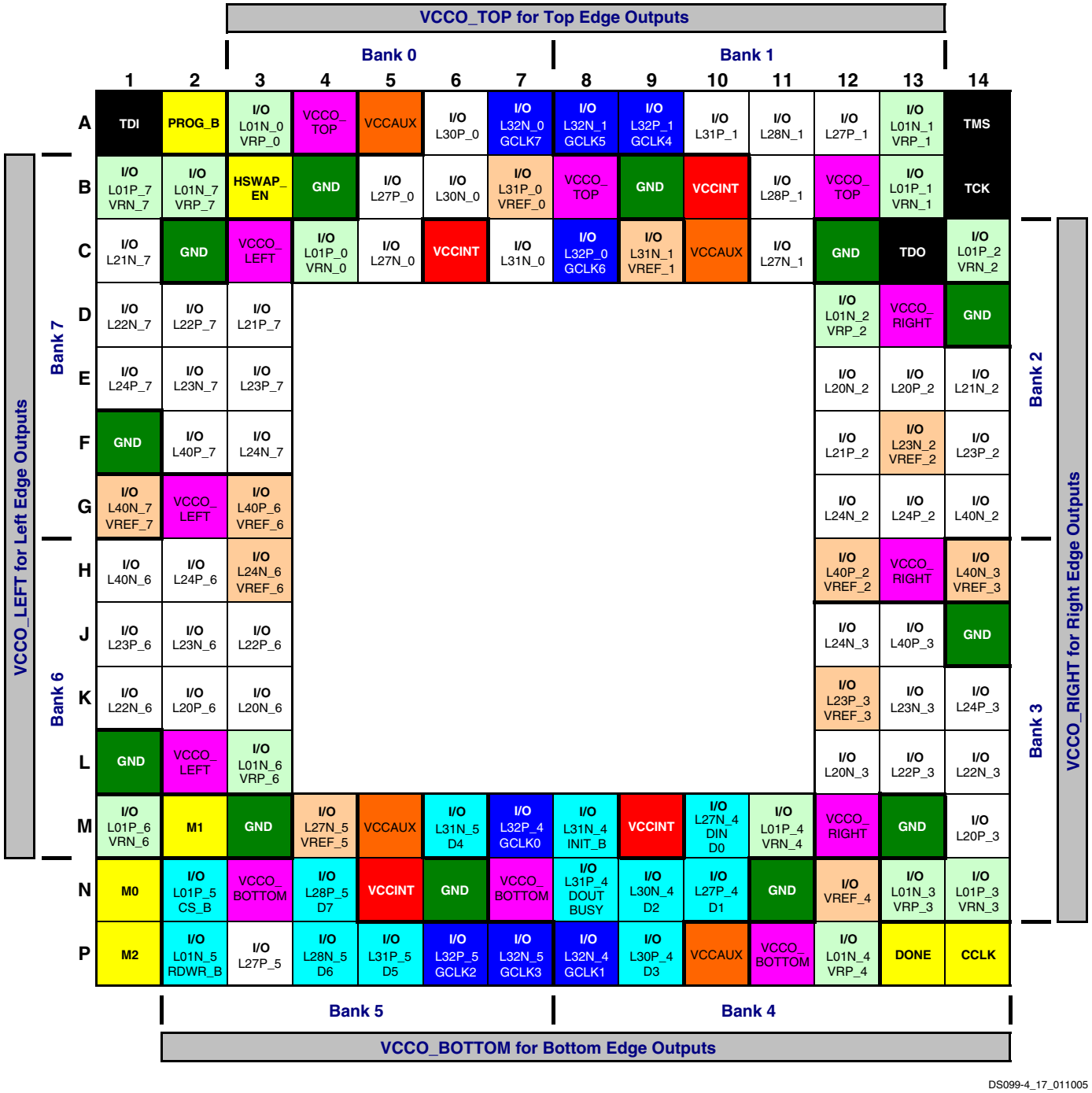
Table 70: **Spartan-3 FPGA Pin Definitions *(Cont'd)***

Pin Name	Direction	Description
GCLK: Global clock buffer inputs		
IO_Lxxy_#/GCLK0, IO_Lxxy_#/GCLK1, IO_Lxxy_#/GCLK2, IO_Lxxy_#/GCLK3, IO_Lxxy_#/GCLK4, IO_Lxxy_#/GCLK5, IO_Lxxy_#/GCLK6, IO_Lxxy_#/GCLK7	Input if connected to global clock buffers Otherwise, same as I/O	**Global Buffer Input:** Direct input to a low-skew global clock buffer. If not connected to a global clock buffer, this pin is a user I/O.
VREF: I/O bank input reference voltage pins		
IO_Lxxy_#/VREF_# or IO/VREF_#	Voltage supply input when VREF pins are used within a bank. Otherwise, same as I/O	**Input Buffer Reference Voltage for Special I/O Standards (per bank):** If required to support special I/O standards, all the VREF pins within a bank connect to a input threshold voltage source. If not used as input reference voltage pins, these pins are available as individual user-I/O pins.
CONFIG: Dedicated configuration pins (pull-up resistor to VCCAUX always active during configuration, regardless of HSWAP_EN pin)		
CCLK	Input in Slave configuration modes Output in Master configuration modes	**Configuration Clock:** The configuration clock signal synchronizes configuration data. This pin has an internal pull-up resistor to VCCAUX during configuration.
PROG_B	Input	**Program/Configure Device:** Active Low asynchronous reset to configuration logic. Asserting PROG_B Low for an extended period delays the configuration process. This pin has an internal pull-up resistor to VCCAUX during configuration.
DONE	Bidirectional with open-drain or totem-pole Output	**Configuration Done, Delay Start-up Sequence:** A Low-to-High output transition on this bidirectional pin signals the end of the configuration process. The FPGA produces a Low-to-High transition on this pin to indicate that the configuration process is complete. The DriveDone bitstream generation option defines whether this pin functions as a totem-pole output that actively drives High or as an open-drain output. An open-drain output requires a pull-up resistor to produce a High logic level. The open-drain option permits the DONE lines of multiple FPGAs to be tied together, so that the common node transitions High only after all of the FPGAs have completed configuration. Externally holding the open-drain output Low delays the start-up sequence, which marks the transition to user mode.
M0, M1, M2	Input	**Configuration Mode Selection:** These inputs select the configuration mode. The logic levels applied to the mode pins are sampled on the rising edge of INIT_B. See Table 75. These pins have an internal pull-up resistor to VCCAUX during configuration, making Slave Serial the default configuration mode.
HSWAP_EN	Input	**Disable Pull-up Resistors During Configuration:** A Low on this pin enables pull-up resistors on all pins that are not actively involved in the configuration process. A High value disables all pull-ups, allowing the non-configuration pins to float.
JTAG: JTAG interface pins (pull-up resistor to VCCAUX always active during configuration, regardless of HSWAP_EN pin)		
TCK	Input	**JTAG Test Clock:** The TCK clock signal synchronizes all JTAG port operations. This pin has an internal pull-up resistor to VCCAUX during configuration.

Table 79: **Pin Behavior After Power-Up, During Configuration *(Cont'd)***

Pin Name	Configuration Mode Settings <M2:M1:M0>					Bitstream Configuration Option
	Serial Modes		SelectMap Parallel Modes		JTAG Mode <1:0:1>	
	Master <0:0:0>	Slave <1:1:1>	Master <0:1:1>	Slave <1:1:0>		
IO_Lxxy_#/ D5			D5 (I/O)	D5 (I/O)		Persist UnusedPin
IO_Lxxy_#/ D6			D6 (I/O)	D6 (I/O)		Persist UnusedPin
IO_Lxxy_#/ D7			D7 (I/O)	D7 (I/O)		Persist UnusedPin
IO_Lxxy_#/ CS_B			CS_B (I)	CS_B (I)		Persist UnusedPin
IO_Lxxy_#/ RDWR_B			RDWR_B (I)	RDWR_B (I)		Persist UnusedPin
IO_Lxxy_#/ BUSY/DOUT	DOUT (O)	DOUT (O)	BUSY (O)	BUSY (O)		Persist UnusedPin
DUAL: Dual-purpose configuration pins (INIT_B has a pull-up resistor to VCCO_4 or VCCO_BOTTOM always active during configuration, regardless of HSWAP_EN pin)						
IO_Lxxy_#/ INIT_B	INIT_B (I/OD)	INIT_B (I/OD)	INIT_B (I/OD)	INIT_B (I/OD)		UnusedPin
DCI: Digitally Controlled Impedance reference resistor input pins						
IO_Lxxy_#/ VRN_#						UnusedPin
IO/VRN_#						UnusedPin
IO_Lxxy_#/ VRP_#						UnusedPin
IO/VRP_#						UnusedPin
GCLK: Global clock buffer inputs						
IO_Lxxy_#/ GCLK0 through GCLK7						UnusedPin
VREF: I/O bank input reference voltage pins						
IO_Lxxy_#/ VREF_#						UnusedPin
IO/VREF_#						UnusedPin
CONFIG: Dedicated configuration pins (pull-up resistor to VCCAUX always active during configuration, regardless of HSWAP_EN pin)						
CCLK	CCLK (I/O)	CCLK (I)	CCLK (I/O)	CCLK (I)		CclkPin ConfigRate
PROG_B	PROG_B (I) (pull-up)	PROG_B (I) (pull-up)	PROG_B (I) (pull-up)	PROG_B (I) (pull-up)	PROG_B (I), Via JPROG_B instruction	ProgPin
DONE	DONE (I/OD)	DONE (I/OD)	DONE (I/OD)	DONE (I/OD)	DONE (I/OD)	DriveDone DonePin DonePipe
M2	M2=0 (I)	M2=1 (I)	M2=0 (I)	M2=1 (I)	M2=1 (I)	M2Pin
M1	M1=0 (I)	M1=1 (I)	M1=1 (I)	M1=1 (I)	M1=0 (I)	M1Pin
M0	M0=0 (I)	M0=1 (I)	M0=1 (I)	M0=0 (I)	M0=1 (I)	M0Pin
HSWAP_EN	HSWAP_EN (I)	HSWAP_EN (I)	HSWAP_EN (I)	HSWAP_EN (I)	HSWAP_EN (I)	HswapenPin

CP132 Footprint



DS099-4_17_011005

Figure 45: **CP132 Package Footprint (Top View). Note pin 1 indicator in top-left corner and logo orientation.**

44	**I/O:** Unrestricted, general-purpose user I/O	12	**DUAL:** Configuration pin, then possible user I/O	11	**VREF:** User I/O or input voltage reference for bank
14	**DCI:** User I/O or reference resistor input for bank	8	**GCLK:** User I/O, input, or global buffer input	12	**VCCO:** Output voltage supply for bank
7	**CONFIG:** Dedicated configuration pins	4	**JTAG:** Dedicated JTAG port pins	4	**VCCINT:** Internal core voltage supply (+1.2V)
0	**N.C.:** No unconnected pins in this package	12	**GND:** Ground	4	**VCCAUX:** Auxiliary voltage supply (+2.5V)

Table 93: **PQ208 Package Pinout *(Cont'd)***

Bank	XC3S50 Pin Name	XC3S200, XC3S400 Pin Names	PQ208 Pin Number	Type
N/A	GND	GND	P14	GND
N/A	GND	GND	P25	GND
N/A	VCCAUX	VCCAUX	P193	VCCAUX
N/A	VCCAUX	VCCAUX	P173	VCCAUX
N/A	VCCAUX	VCCAUX	P142	VCCAUX
N/A	VCCAUX	VCCAUX	P121	VCCAUX
N/A	VCCAUX	VCCAUX	P89	VCCAUX
N/A	VCCAUX	VCCAUX	P69	VCCAUX
N/A	VCCAUX	VCCAUX	P38	VCCAUX
N/A	VCCAUX	VCCAUX	P17	VCCAUX
N/A	VCCINT	VCCINT	P192	VCCINT
N/A	VCCINT	VCCINT	P174	VCCINT
N/A	VCCINT	VCCINT	P88	VCCINT
N/A	VCCINT	VCCINT	P70	VCCINT
VCCAUX	CCLK	CCLK	P104	CONFIG
VCCAUX	DONE	DONE	P103	CONFIG
VCCAUX	HSWAP_EN	HSWAP_EN	P206	CONFIG
VCCAUX	M0	M0	P55	CONFIG
VCCAUX	M1	M1	P54	CONFIG
VCCAUX	M2	M2	P56	CONFIG
VCCAUX	PROG_B	PROG_B	P207	CONFIG
VCCAUX	TCK	TCK	P159	JTAG
VCCAUX	TDI	TDI	P208	JTAG
VCCAUX	TDO	TDO	P158	JTAG
VCCAUX	TMS	TMS	P160	JTAG

User I/Os by Bank

Table 94 indicates how the available user-I/O pins are distributed between the eight I/O banks for the XC3S50 in the PQ208 package. Similarly, Table 95 shows how the available user-I/O pins are distributed between the eight I/O banks for the XC3S200 and XC3S400 in the PQ208 package.

Table 94: **User I/Os Per Bank for XC3S50 in PQ208 Package**

Package Edge	I/O Bank	Maximum I/O	All Possible I/O Pins by Type				
			I/O	DUAL	DCI	VREF	GCLK
Top	0	15	9	0	2	2	2
	1	15	9	0	2	2	2
Right	2	16	13	0	2	2	0
	3	16	12	0	2	2	0
Bottom	4	15	3	6	2	2	2
	5	15	3	6	2	2	2
Left	6	16	12	0	2	2	0
	7	16	12	0	2	2	0

Table 95: **User I/Os Per Bank for XC3S200 and XC3S400 in PQ208 Package**

Package Edge	I/O Bank	Maximum I/O	All Possible I/O Pins by Type				
			I/O	DUAL	DCI	VREF	GCLK
Top	0	16	9	0	2	3	2
	1	15	9	0	2	2	2
Right	2	19	14	0	2	3	0
	3	20	15	0	2	3	0
Bottom	4	17	4	6	2	3	2
	5	15	3	6	2	2	2
Left	6	19	14	0	2	3	0
	7	20	15	0	2	3	0

User I/Os by Bank

Table 97 indicates how the available user-I/O pins are distributed between the eight I/O banks on the FT256 package.

Table 97: **User I/Os Per Bank in FT256 Package**

Package Edge	I/O Bank	Maximum I/O	All Possible I/O Pins by Type				
			I/O	DUAL	DCI	VREF	GCLK
Top	0	20	13	0	2	3	2
	1	20	13	0	2	3	2
Right	2	23	18	0	2	3	0
	3	23	18	0	2	3	0
Bottom	4	21	8	6	2	3	2
	5	20	7	6	2	3	2
Left	6	23	18	0	2	3	0
	7	23	18	0	2	3	0

Table 100: **FG456 Package Pinout *(Cont'd)***

Bank	3S400 Pin Name	3S1000, 3S1500, 3S2000 Pin Name	FG456 Pin Number	Type
6	N.C. (◆)	IO_L28N_6	R5	I/O
6	N.C. (◆)	IO_L28P_6	P6	I/O
6	N.C. (◆)	IO_L29N_6	R2	I/O
6	N.C. (◆)	IO_L29P_6	R1	I/O
6	N.C. (◆)	IO_L31N_6	P5	I/O
6	N.C. (◆)	IO_L31P_6	P4	I/O
6	N.C. (◆)	IO_L32N_6	P2	I/O
6	N.C. (◆)	IO_L32P_6	P1	I/O
6	N.C. (◆)	IO_L33N_6	N6	I/O
6	N.C. (◆)	IO_L33P_6	N5	I/O
6	IO_L34N_6/VREF_6	IO_L34N_6/VREF_6	N4	VREF
6	IO_L34P_6	IO_L34P_6	N3	I/O
6	IO_L35N_6	IO_L35N_6	N2	I/O
6	IO_L35P_6	IO_L35P_6	N1	I/O
6	IO_L38N_6	IO_L38N_6	M6	I/O
6	IO_L38P_6	IO_L38P_6	M5	I/O
6	IO_L39N_6	IO_L39N_6	M4	I/O
6	IO_L39P_6	IO_L39P_6	M3	I/O
6	IO_L40N_6	IO_L40N_6	M2	I/O
6	IO_L40P_6/VREF_6	IO_L40P_6/VREF_6	M1	VREF
6	VCCO_6	VCCO_6	M7	VCCO
6	VCCO_6	VCCO_6	N7	VCCO
6	VCCO_6	VCCO_6	P7	VCCO
6	VCCO_6	VCCO_6	R3	VCCO
6	VCCO_6	VCCO_6	R6	VCCO
7	IO	IO	C2	I/O
7	IO_L01N_7/VRP_7	IO_L01N_7/VRP_7	C3	DCI
7	IO_L01P_7/VRN_7	IO_L01P_7/VRN_7	C4	DCI
7	IO_L16N_7	IO_L16N_7	D1	I/O
7	IO_L16P_7/VREF_7	IO_L16P_7/VREF_7	C1	VREF
7	IO_L17N_7	IO_L17N_7	E4	I/O
7	IO_L17P_7	IO_L17P_7	D4	I/O
7	IO_L19N_7/VREF_7	IO_L19N_7/VREF_7	D3	VREF
7	IO_L19P_7	IO_L19P_7	D2	I/O
7	IO_L20N_7	IO_L20N_7	F4	I/O
7	IO_L20P_7	IO_L20P_7	E3	I/O
7	IO_L21N_7	IO_L21N_7	E1	I/O
7	IO_L21P_7	IO_L21P_7	E2	I/O
7	IO_L22N_7	IO_L22N_7	G6	I/O
7	IO_L22P_7	IO_L22P_7	F5	I/O

Table 103: **FG676 Package Pinout *(Cont'd)***

Bank	XC3S1000 Pin Name	XC3S1500 Pin Name	XC3S2000 Pin Name	XC3S4000 Pin Name	XC3S5000 Pin Name	FG676 Pin Number	Type
6	IO_L20N_6	IO_L20N_6	IO_L20N_6	IO_L20N_6	IO_L20N_6	V7	I/O
6	IO_L20P_6	IO_L20P_6	IO_L20P_6	IO_L20P_6	IO_L20P_6	U7	I/O
6	IO_L21N_6	IO_L21N_6	IO_L21N_6	IO_L21N_6	IO_L21N_6	V5	I/O
6	IO_L21P_6	IO_L21P_6	IO_L21P_6	IO_L21P_6	IO_L21P_6	V4	I/O
6	IO_L22N_6	IO_L22N_6	IO_L22N_6	IO_L22N_6	IO_L22N_6	V3	I/O
6	IO_L22P_6	IO_L22P_6	IO_L22P_6	IO_L22P_6	IO_L22P_6	V2	I/O
6	IO_L23N_6	IO_L23N_6	IO_L23N_6	IO_L23N_6	IO_L23N_6	U6	I/O
6	IO_L23P_6	IO_L23P_6	IO_L23P_6	IO_L23P_6	IO_L23P_6	U5	I/O
6	IO_L24N_6/VREF_6	IO_L24N_6/VREF_6	IO_L24N_6/VREF_6	IO_L24N_6/VREF_6	IO_L24N_6/VREF_6	U4	VREF
6	IO_L24P_6	IO_L24P_6	IO_L24P_6	IO_L24P_6	IO_L24P_6	U3	I/O
6	IO_L26N_6	IO_L26N_6	IO_L26N_6	IO_L26N_6	IO_L26N_6	U2	I/O
6	IO_L26P_6	IO_L26P_6	IO_L26P_6	IO_L26P_6	IO_L26P_6	U1	I/O
6	IO_L27N_6	IO_L27N_6	IO_L27N_6	IO_L27N_6	IO_L27N_6	T8	I/O
6	IO_L27P_6	IO_L27P_6	IO_L27P_6	IO_L27P_6	IO_L27P_6	T7	I/O
6	IO_L28N_6	IO_L28N_6	IO_L28N_6	IO_L28N_6	IO_L28N_6	T6	I/O
6	IO_L28P_6	IO_L28P_6	IO_L28P_6	IO_L28P_6	IO_L28P_6	T5	I/O
6	IO_L29N_6	IO_L29N_6	IO_L29N_6	IO_L29N_6	IO_L29N_6	T2	I/O
6	IO_L29P_6	IO_L29P_6	IO_L29P_6	IO_L29P_6	IO_L29P_6	T1	I/O
6	IO_L31N_6	IO_L31N_6	IO_L31N_6	IO_L31N_6	IO_L31N_6	R8	I/O
6	IO_L31P_6	IO_L31P_6	IO_L31P_6	IO_L31P_6	IO_L31P_6	R7	I/O
6	IO_L32N_6	IO_L32N_6	IO_L32N_6	IO_L32N_6	IO_L32N_6	R6	I/O
6	IO_L32P_6	IO_L32P_6	IO_L32P_6	IO_L32P_6	IO_L32P_6	R5	I/O
6	IO_L33N_6	IO_L33N_6	IO_L33N_6	IO_L33N_6	IO_L33N_6	T4	I/O
6	IO_L33P_6	IO_L33P_6	IO_L33P_6	IO_L33P_6	IO_L33P_6	R3	I/O
6	IO_L34N_6/VREF_6	IO_L34N_6/VREF_6	IO_L34N_6/VREF_6	IO_L34N_6/VREF_6	IO_L34N_6/VREF_6	R2	VREF
6	IO_L34P_6	IO_L34P_6	IO_L34P_6	IO_L34P_6	IO_L34P_6	R1	I/O
6	IO_L35N_6	IO_L35N_6	IO_L35N_6	IO_L35N_6	IO_L35N_6	P8	I/O
6	IO_L35P_6	IO_L35P_6	IO_L35P_6	IO_L35P_6	IO_L35P_6	P7	I/O
6	IO_L38N_6	IO_L38N_6	IO_L38N_6	IO_L38N_6	IO_L38N_6	P6	I/O
6	IO_L38P_6	IO_L38P_6	IO_L38P_6	IO_L38P_6	IO_L38P_6	P5	I/O
6	IO_L39N_6	IO_L39N_6	IO_L39N_6	IO_L39N_6	IO_L39N_6	P4	I/O
6	IO_L39P_6	IO_L39P_6	IO_L39P_6	IO_L39P_6	IO_L39P_6	P3	I/O
6	IO_L40N_6	IO_L40N_6	IO_L40N_6	IO_L40N_6	IO_L40N_6	P2	I/O
6	IO_L40P_6/VREF_6	IO_L40P_6/VREF_6	IO_L40P_6/VREF_6	IO_L40P_6/VREF_6	IO_L40P_6/VREF_6	P1	VREF
6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	P9	VCCO
6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	P10	VCCO
6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	R9	VCCO
6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	T3	VCCO
6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	T9	VCCO
6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	U8	VCCO
6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	V8	VCCO
6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	VCCO_6	Y3	VCCO
7	IO_L01N_7/VRP_7	IO_L01N_7/VRP_7	IO_L01N_7/VRP_7	IO_L01N_7/VRP_7	IO_L01N_7/VRP_7	F5	DCI

FG676 Footprint

Left Half of Package (Top View)

XC3S1000 (391 max. user I/O)

315 **I/O:** Unrestricted, general-purpose user I/O

40 **VREF:** User I/O or input voltage reference for bank

98 **N.C.:** Unconnected pins for XC3S1000 (◆)

XC3S1500 (487 max user I/O)

403 **I/O:** Unrestricted, general-purpose user I/O

48 **VREF:** User I/O or input voltage reference for bank

2 **N.C.:** Unconnected pins for XC3S1500 (■)

XC3S2000, XC3S4000, XC3S5000 (489 max user I/O)

405 **I/O:** Unrestricted, general-purpose user I/O

48 **VREF:** User I/O or input voltage reference for bank

0 **N.C.:** No unconnected pins

All devices

12 **DUAL:** Configuration pin, then possible user I/O

8 **GCLK:** User I/O or global clock buffer input

16 **DCI:** User I/O or reference resistor input for bank

7 **CONFIG:** Dedicated configuration pins

4 **JTAG:** Dedicated JTAG port pins

20 **VCCINT:** Internal core voltage supply (+1.2V)

64 **VCCO:** Output voltage supply for bank

16 **VCCAUX:** Auxiliary voltage supply (+2.5V)

76 **GND:** Ground

	Bank 0												
	1	2	3	4	5	6	7	8	9	10	11	12	13
A	GND	VCCAUX	I/O	I/O L05P_0 VREF_0	I/O	I/O	I/O L10P_0	I/O L15P_0	VCCAUX	I/O L23P_0 ◆	I/O L26P_0 VREF_0 ◆	I/O L29P_0	I/O L32P_0 GCLK6
B	VCCAUX	GND	I/O VREF_0	I/O L05N_0	I/O L06P_0	I/O L08P_0	I/O L10N_0	I/O L15N_0	I/O L18P_0 ◆	I/O L23N_0 ◆	I/O L26N_0 ◆	I/O L29N_0	I/O L32N_0 GCLK7
C	TDI	HSWAP_EN	GND	I/O	I/O L06N_0	I/O L08N_0	VCCO_0	I/O ◆	I/O L18N_0 ◆	I/O L22P_0	VCCO_0	I/O	I/O L31P_0 VREF_0
D	I/O L03N_7 VREF_7	I/O L03P_7	PROG_B	GND	I/O L01P_0 VRN_0	I/O L07P_0	I/O L09P_0	I/O L12P_0 ◆	I/O L17P_0 ◆	I/O L22N_0	I/O L25P_0	GND	I/O L31N_0
E	I/O L06N_7 ◆	I/O L06P_7 ◆	I/O L02N_7	I/O L02P_7	I/O L01N_0 VRP_0	I/O L07N_0	I/O L09N_0	I/O L12N_0 ◆	I/O L17N_0 ◆	I/O L19P_0	I/O L25N_0	I/O L28P_0	I/O
F	I/O L09N_7 ◆	I/O L09P_7 ◆	I/O L07N_7 ◆	I/O L07P_7 ◆	I/O L01N_7 VRP_7	I/O L01P_7 VRN_7	I/O VREF_0	I/O L11P_0 ◆	I/O L16P_0	I/O L19N_0	I/O L24P_0	I/O L28N_0	I/O L30P_0
G	I/O L14N_7	I/O L14P_7	VCCO_7	I/O L08N_7 ◆	I/O L08P_7 ◆	I/O L05N_7 ◆	I/O L05P_7 ◆	I/O L11N_0 ◆	I/O L16N_0	I/O VREF_0	I/O L24N_0	I/O L27N_0	I/O L30N_0
H	I/O L19N_7 VREF_7	I/O L19P_7	I/O L17N_7	I/O L17P_7	I/O L16P_7 VREF_7	I/O L10N_7 ◆	I/O L10P_7 VREF_7 ◆	VCCINT	VCCO_0	VCCO_0	I/O	I/O	I/O L27P_0
J	VCCAUX	I/O L22N_7	I/O L22P_7	I/O L21N_7	I/O L21P_7	I/O L16N_7	I/O L20P_7	VCCO_7	VCCINT	VCCINT	VCCO_0	VCCO_0	VCCO_0
K	I/O L26N_7	I/O L26P_7	I/O L24N_7	I/O L24P_7	I/O L23N_7	I/O L23P_7	I/O L20N_7	VCCO_7	VCCINT	VCCINT	GND	GND	VCCO_0
L	I/O L29N_7	I/O L29P_7	VCCO_7	I/O L33P_7	I/O L28N_7	I/O L28P_7	I/O L27N_7	I/O L27P_7 VREF_7	VCCO_7	GND	GND	GND	GND
M	I/O L34N_7	I/O L34P_7	I/O L33N_7	GND	I/O L32P_7	I/O L32N_7	I/O L31N_7	I/O L31P_7	VCCO_7	GND	GND	GND	GND
N	I/O L40N_7 VREF_7	I/O L40P_7	I/O L39N_7	I/O L39P_7	I/O L38N_7	I/O L38P_7	I/O L35N_7	I/O L35P_7	VCCO_7	VCCO_7	GND	GND	GND
P	I/O L40P_6 VREF_6	I/O L40N_6	I/O L39P_6	I/O L39N_6	I/O L38P_6	I/O L38N_6	I/O L35P_6	I/O L35N_6	VCCO_6	VCCO_6	GND	GND	GND
R	I/O L34P_6	I/O L34N_6 VREF_6	I/O L33P_6	GND	I/O L32P_6	I/O L32N_6	I/O L31P_6	I/O L31N_6	VCCO_6	GND	GND	GND	GND
T	I/O L29P_6	I/O L29N_6	VCCO_6	I/O L33N_6	I/O L28P_6	I/O L28N_6	I/O L27P_6	I/O L27N_6	VCCO_6	GND	GND	GND	GND
U	I/O L26P_6	I/O L26N_6	I/O L24P_6	I/O L24N_6 VREF_6	I/O L23P_6	I/O L23N_6	I/O L20P_6	VCCO_6	VCCINT	VCCINT	GND	GND	VCCO_5
V	VCCAUX	I/O L22P_6	I/O L22N_6	I/O L21P_6	I/O L21N_6	I/O L16N_6	I/O L20N_6	VCCO_6	VCCINT	VCCINT	VCCO_5	VCCO_5	VCCO_5
W	I/O L19P_6	I/O L19N_6	I/O L17P_6 VREF_6	I/O L17N_6	I/O L16P_6	I/O L14P_6	I/O L14N_6	VCCINT	VCCO_5	VCCO_5	I/O L24P_5	I/O L27P_5	I/O L30P_5
Y	I/O L10P_6 ◆	I/O L10N_6 ◆	VCCO_6	I/O L08P_6 ◆	I/O L08N_6 ◆	I/O L06P_6 ◆	I/O L06N_6 ◆	I/O	I/O L16P_5	I/O L19P_5 VREF_5	I/O L24N_5	I/O L27N_5 VREF_5	I/O L30N_5
AA	I/O L09P_6 ◆	I/O L09N_6 VREF_6 ◆	I/O L07P_6 ◆	I/O L07N_6 ◆	I/O ◆■	I/O L05P_5	I/O	I/O L11P_5 ◆	I/O L16N_5	I/O L19N_5	I/O L25P_5	I/O L28P_5 D7	I/O
AB	I/O L05P_6 ◆	I/O L05N_6 ◆	I/O L02P_6	I/O L02N_6	I/O L01P_5 CS_B	I/O L05N_5	I/O L09P_5	I/O L11N_5 VREF_5 ◆	I/O	I/O L22P_5	I/O L25N_5	I/O L28N_5 D6	I/O L31P_5 D5
AC	I/O L03P_6	I/O L03N_6 VREF_6	M1	GND	I/O L01N_5 RDWR_B	I/O L07P_5	I/O L09N_5	I/O L12P_5 ◆	I/O ◆	I/O L22N_5	I/O	GND	I/O L31N_5 D4
AD	I/O L01P_6 VRN_6	I/O L01N_6 VRP_6	GND	I/O L04P_5	I/O L06P_5	I/O L07N_5	VCCO_5	I/O L12N_5 ◆	I/O L18P_5 ◆	I/O	VCCO_5	I/O	I/O L32P_5 GCLK2
AE	VCCAUX	GND	M0	I/O L04N_5	I/O L06N_5	I/O L08P_5	I/O L10P_5 VRN_5	I/O L15P_5	I/O L18N_5 ◆	I/O L23P_5 ◆	I/O L26P_5 ◆	I/O L29P_5 VREF_5	I/O L32N_5 GCLK3
AF	GND	VCCAUX	M2	I/O	I/O VREF_5	I/O L08N_5	I/O L10N_5 VRP_5	I/O L15N_5	VCCAUX	I/O L23N_5 ◆	I/O L26N_5 ◆	I/O L29N_5	I/O VREF_5

Bank 7 (rows H–N) · Bank 6 (rows P–AF) · Bank 5

DS099-4 12a 030203

Figure 53: **FG676 Package Footprint (Top View)**

FG900: 900-lead Fine-pitch Ball Grid Array

The 900-lead fine-pitch ball grid array package, FG900, supports three different Spartan-3 devices, including the XC3S2000, the XC3S4000, and the XC3S5000. The footprints for the XC3S4000 and XC3S5000 are identical, as shown in Table 107 and Figure 55. The XC3S2000, however, has fewer I/O pins which consequently results in 68 unconnected pins on the FG900 package, labeled as “N.C.” In Table 107 and Figure 55, these unconnected pins are indicated with a black diamond symbol (◆).

All the package pins appear in Table 107 and are sorted by bank number, then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

If there is a difference between the XC3S2000 pinout and the pinout for the XC3S4000 and XC3S5000, then that difference is highlighted in Table 107. If the table entry is shaded, then there is an unconnected pin on the XC3S2000 that maps to a user-I/O pin on the XC3S4000 and XC3S5000.

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at http://www.xilinx.com/support/documentation/data_ sheets/s3_pin.zip.

Pinout Table

Table 107: **FG900 Package Pinout**

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
0	IO	IO	E15	I/O
0	IO	IO	K15	I/O
0	IO	IO	D13	I/O
0	IO	IO	K13	I/O
0	IO	IO	G8	I/O
0	IO/VREF_0	IO/VREF_0	F9	VREF
0	IO/VREF_0	IO/VREF_0	C4	VREF
0	IO_L01N_0/VRP_0	IO_L01N_0/VRP_0	B4	DCI
0	IO_L01P_0/VRN_0	IO_L01P_0/VRN_0	A4	DCI
0	IO_L02N_0	IO_L02N_0	B5	I/O
0	IO_L02P_0	IO_L02P_0	A5	I/O
0	IO_L03N_0	IO_L03N_0	D5	I/O
0	IO_L03P_0	IO_L03P_0	E6	I/O
0	IO_L04N_0	IO_L04N_0	C6	I/O
0	IO_L04P_0	IO_L04P_0	B6	I/O
0	IO_L05N_0	IO_L05N_0	F6	I/O
0	IO_L05P_0/VREF_0	IO_L05P_0/VREF_0	F7	VREF
0	IO_L06N_0	IO_L06N_0	D7	I/O
0	IO_L06P_0	IO_L06P_0	C7	I/O
0	IO_L07N_0	IO_L07N_0	F8	I/O
0	IO_L07P_0	IO_L07P_0	E8	I/O
0	IO_L08N_0	IO_L08N_0	D8	I/O
0	IO_L08P_0	IO_L08P_0	C8	I/O
0	IO_L09N_0	IO_L09N_0	B8	I/O
0	IO_L09P_0	IO_L09P_0	A8	I/O

Table 107: **FG900 Package Pinout *(Cont'd)***

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
0	IO_L10N_0	IO_L10N_0	J9	I/O
0	IO_L10P_0	IO_L10P_0	H9	I/O
0	IO_L11N_0	IO_L11N_0	G10	I/O
0	IO_L11P_0	IO_L11P_0	F10	I/O
0	IO_L12N_0	IO_L12N_0	C10	I/O
0	IO_L12P_0	IO_L12P_0	B10	I/O
0	IO_L13N_0	IO_L13N_0	J10	I/O
0	IO_L13P_0	IO_L13P_0	K11	I/O
0	IO_L14N_0	IO_L14N_0	H11	I/O
0	IO_L14P_0	IO_L14P_0	G11	I/O
0	IO_L15N_0	IO_L15N_0	F11	I/O
0	IO_L15P_0	IO_L15P_0	E11	I/O
0	IO_L16N_0	IO_L16N_0	D11	I/O
0	IO_L16P_0	IO_L16P_0	C11	I/O
0	IO_L17N_0	IO_L17N_0	B11	I/O
0	IO_L17P_0	IO_L17P_0	A11	I/O
0	IO_L18N_0	IO_L18N_0	K12	I/O
0	IO_L18P_0	IO_L18P_0	J12	I/O
0	IO_L19N_0	IO_L19N_0	H12	I/O
0	IO_L19P_0	IO_L19P_0	G12	I/O
0	IO_L20N_0	IO_L20N_0	F12	I/O
0	IO_L20P_0	IO_L20P_0	E12	I/O
0	IO_L21N_0	IO_L21N_0	D12	I/O
0	IO_L21P_0	IO_L21P_0	C12	I/O
0	IO_L22N_0	IO_L22N_0	B12	I/O
0	IO_L22P_0	IO_L22P_0	A12	I/O
0	IO_L23N_0	IO_L23N_0	J13	I/O
0	IO_L23P_0	IO_L23P_0	H13	I/O
0	IO_L24N_0	IO_L24N_0	F13	I/O
0	IO_L24P_0	IO_L24P_0	E13	I/O
0	IO_L25N_0	IO_L25N_0	B13	I/O
0	IO_L25P_0	IO_L25P_0	A13	I/O
0	IO_L26N_0	IO_L26N_0	K14	I/O
0	IO_L26P_0/VREF_0	IO_L26P_0/VREF_0	J14	VREF
0	IO_L27N_0	IO_L27N_0	G14	I/O
0	IO_L27P_0	IO_L27P_0	F14	I/O
0	IO_L28N_0	IO_L28N_0	C14	I/O
0	IO_L28P_0	IO_L28P_0	B14	I/O
0	IO_L29N_0	IO_L29N_0	J15	I/O
0	IO_L29P_0	IO_L29P_0	H15	I/O

Table 107: **FG900 Package Pinout *(Cont'd)***

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
6	IO_L28P_6	IO_L28P_6	W1	I/O
6	IO_L29N_6	IO_L29N_6	W10	I/O
6	IO_L29P_6	IO_L29P_6	V10	I/O
6	N.C. (◆)	IO_L30N_6	V9	I/O
6	N.C. (◆)	IO_L30P_6	V8	I/O
6	IO_L31N_6	IO_L31N_6	W5	I/O
6	IO_L31P_6	IO_L31P_6	V6	I/O
6	IO_L32N_6	IO_L32N_6	V5	I/O
6	IO_L32P_6	IO_L32P_6	V4	I/O
6	IO_L33N_6	IO_L33N_6	V2	I/O
6	IO_L33P_6	IO_L33P_6	V1	I/O
6	IO_L34N_6/VREF_6	IO_L34N_6/VREF_6	U10	VREF
6	IO_L34P_6	IO_L34P_6	U9	I/O
6	IO_L35N_6	IO_L35N_6	U7	I/O
6	IO_L35P_6	IO_L35P_6	U6	I/O
6	N.C. (◆)	IO_L36N_6	U3	I/O
6	N.C. (◆)	IO_L36P_6	U2	I/O
6	IO_L37N_6	IO_L37N_6	T10	I/O
6	IO_L37P_6	IO_L37P_6	T9	I/O
6	IO_L38N_6	IO_L38N_6	T6	I/O
6	IO_L38P_6	IO_L38P_6	T5	I/O
6	IO_L39N_6	IO_L39N_6	T4	I/O
6	IO_L39P_6	IO_L39P_6	T3	I/O
6	IO_L40N_6	IO_L40N_6	T2	I/O
6	IO_L40P_6/VREF_6	IO_L40P_6/VREF_6	T1	VREF
6	N.C. (◆)	IO_L45N_6	Y4	I/O
6	N.C. (◆)	IO_L45P_6	Y3	I/O
6	N.C. (◆)	IO_L52N_6	T8	I/O
6	N.C. (◆)	IO_L52P_6	T7	I/O
6	VCCO_6	VCCO_6	V3	VCCO
6	VCCO_6	VCCO_6	AB3	VCCO
6	VCCO_6	VCCO_6	AF3	VCCO
6	VCCO_6	VCCO_6	AD5	VCCO
6	VCCO_6	VCCO_6	V7	VCCO
6	VCCO_6	VCCO_6	AB7	VCCO
6	VCCO_6	VCCO_6	Y9	VCCO
6	VCCO_6	VCCO_6	U11	VCCO
6	VCCO_6	VCCO_6	V11	VCCO
6	VCCO_6	VCCO_6	W11	VCCO
7	IO	IO	J6	I/O

Table 107: **FG900 Package Pinout *(Cont'd)***

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
N/A	GND	GND	T12	GND
N/A	GND	GND	N13	GND
N/A	GND	GND	P13	GND
N/A	GND	GND	R13	GND
N/A	GND	GND	T13	GND
N/A	GND	GND	U13	GND
N/A	GND	GND	V13	GND
N/A	GND	GND	A14	GND
N/A	GND	GND	E14	GND
N/A	GND	GND	H14	GND
N/A	GND	GND	N14	GND
N/A	GND	GND	P14	GND
N/A	GND	GND	R14	GND
N/A	GND	GND	T14	GND
N/A	GND	GND	U14	GND
N/A	GND	GND	V14	GND
N/A	GND	GND	AC14	GND
N/A	GND	GND	AF14	GND
N/A	GND	GND	AK14	GND
N/A	GND	GND	M15	GND
N/A	GND	GND	N15	GND
N/A	GND	GND	P15	GND
N/A	GND	GND	R15	GND
N/A	GND	GND	T15	GND
N/A	GND	GND	U15	GND
N/A	GND	GND	V15	GND
N/A	GND	GND	W15	GND
N/A	GND	GND	M16	GND
N/A	GND	GND	N16	GND
N/A	GND	GND	P16	GND
N/A	GND	GND	R16	GND
N/A	GND	GND	T16	GND
N/A	GND	GND	U16	GND
N/A	GND	GND	V16	GND
N/A	GND	GND	W16	GND
N/A	GND	GND	A17	GND
N/A	GND	GND	E17	GND
N/A	GND	GND	H17	GND
N/A	GND	GND	N17	GND
N/A	GND	GND	P17	GND